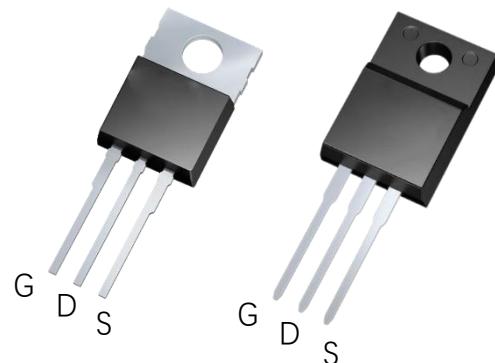


**650V 12A 0.58Ω N-ch Power MOSFET****Description**

WMOS™ D1 is Wayon's 1<sup>st</sup> generation VDMOS family that is dramatic reduction in on-resistance and ultra-low gate charge for applications requiring high power density and high efficiency. And it is very robust and RoHS compliant.

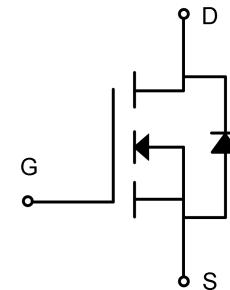
TO-220      TO-220F

**Features**

- $V_{DS}=700V@T_{jmax}$
- Typ. $R_{DS(on)}=0.58\Omega@V_{GS}=10V$
- 100% avalanche tested
- Pb-free, Halogen free

**Applications**

- SMPS
- Charger
- DC-DC

**Absolute Maximum Ratings (T<sub>c</sub>=25°C)**

Parameter	Symbol	WMK12N65D1B	WML12N65D1B	Unit
Drain-source voltage	$V_{DSS}$	650		V
Gate-source voltage	$V_{GS}$	$\pm 30$		V
Continuous drain current	$I_D$	12		A
Pulsed drain current	$I_{DM}$	48		A
Avalanche energy, single pulse	$E_{AS}$	296		mJ
Power dissipation	$P_D$	156	65	W
Derate above 25°C		1.25	0.5	$W/^\circ C$
Operating junction temperature	$T_j$	-55~150		$^\circ C$
Storage temperature	$T_{stg}$	-55~150		$^\circ C$
Continuous diode forward current	$I_S$	12		A
Diode pulse current	$I_{Spulse}$	48		A

**Thermal Characteristic**

Thermal resistance, junction-to-case	$R_{\theta JC}$	0.8	2	$^\circ C/W$
Thermal resistance, junction-to-ambient	$R_{\theta JA}$	62.5	62.5	$^\circ C/W$

**Electrical Characteristics of MOSFET**

				Min.	Typ.	Max.	
Drain-source break down voltage	BV <sub>DSS</sub>	I <sub>D</sub> =250uA, V <sub>GS</sub> =0V	T <sub>C</sub> =25°C	650	-	-	V
Gate threshold voltage	V <sub>GS(th)</sub>	I <sub>D</sub> =250uA, V <sub>DS</sub> =V <sub>GS</sub>	T <sub>J</sub> =25°C	2.0	2.9	4.0	V
Drain-source leakage current	I <sub>DSS</sub>	V <sub>DS</sub> =650V, V <sub>GS</sub> =0V	T <sub>J</sub> =25°C	-	-	1	uA
		V <sub>DS</sub> =520V, V <sub>GS</sub> =0V	T <sub>J</sub> =125°C	-	-	100	uA
Gate-source leakage current,forward	I <sub>GSSF</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =30V	T <sub>J</sub> =25°C	-	-	100	nA
Gate-source leakage current,reverse	I <sub>GSSR</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =-30V	T <sub>J</sub> =25°C	-	-	-100	nA
Drain-source on-state resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =6A	T <sub>J</sub> =25°C	-	0.58	0.74	Ω

**Dynamic Characteristics of MOSFET (T<sub>C</sub>=25°C)**

				Min.	Typ.	Max.	
Input capacitance	C <sub>iss</sub>	f=1MHz, V <sub>DS</sub> =25V, V <sub>GS</sub> =0V	-	2010	-	pF	
Output capacitance	C <sub>oss</sub>		-	161	-	pF	
Reverse transfer capacitance	C <sub>rss</sub>		-	18.5	-	pF	
Gate to source charge	Q <sub>gs</sub>	V <sub>DD</sub> =320V I <sub>D</sub> =12A V <sub>GS</sub> = 0 to 10V	-	10.8	-	nC	
Gate to drain charge	Q <sub>gd</sub>		-	14.4	-	nC	
Total gate charge	Q <sub>g</sub>		-	44.7	-	nC	

**Switching Characteristics of MOSFET (T<sub>C</sub>=25°C)**

				Min.	Typ.	Max.	
Turn-on delay time	t <sub>d on</sub>	V <sub>DS</sub> =320V, I <sub>D</sub> =12A, R <sub>G</sub> =25Ω, V <sub>GS</sub> =0 to 10V	-	29	-	ns	
Rise time	t <sub>r</sub>		-	33	-	ns	
Turn-off delay time	t <sub>d off</sub>		-	143	-	ns	
Fall time	t <sub>f</sub>		-	47	-	ns	

**Characteristics of Body Diode (T<sub>C</sub>=25°C)**

				Min.	Typ.	Max.	
Forward voltage	V <sub>SD</sub>	I <sub>SD</sub> =12A, V <sub>GS</sub> =0V	-	-	1.4	V	
Reverse recovery time	t <sub>rr</sub>	V <sub>DS</sub> =320V, I <sub>s</sub> =12A, V <sub>GS</sub> =0V di/dt=100A/us	-	364	-	ns	
Reverse recovery current	I <sub>rr</sub>		-	37	-	A	
Recovery charge	Q <sub>rr</sub>		-	6.8	-	uC	

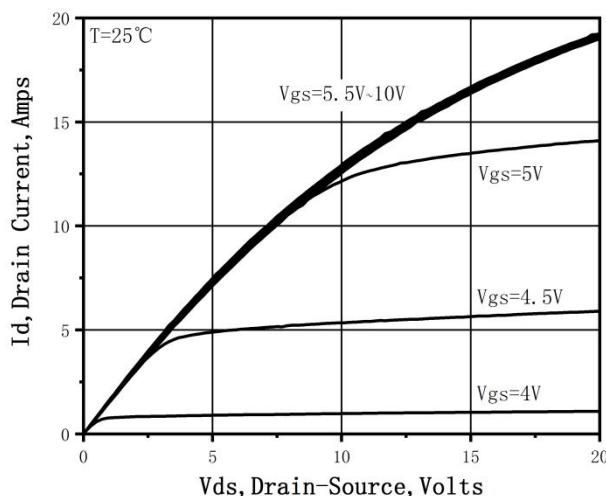


Figure 1. On-Region Characteristics

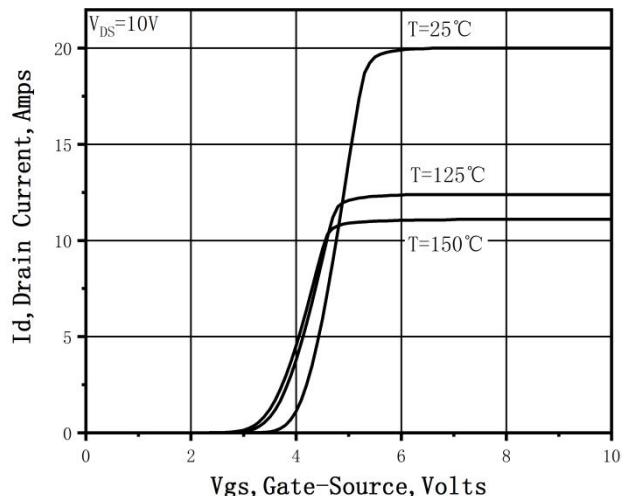


Figure 2. Transfer Characteristics

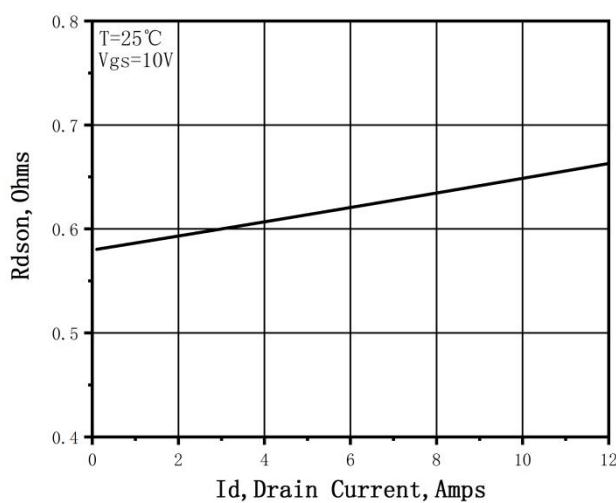


Figure 3. Static Drain-Source On Resistance

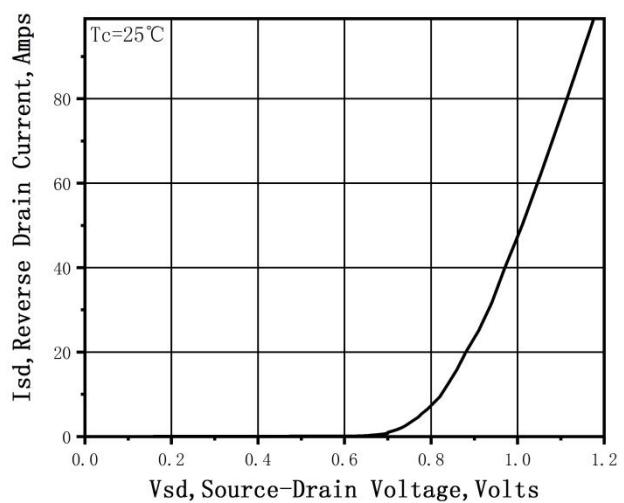
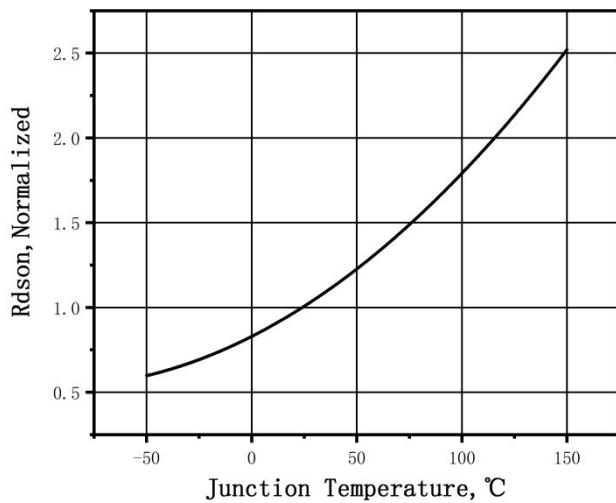
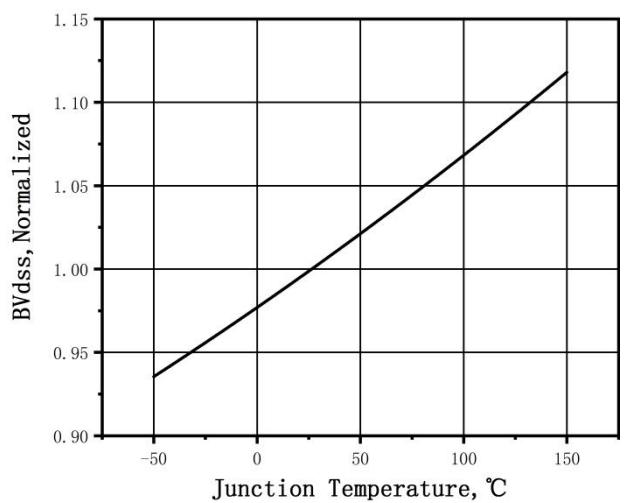


Figure 4. Typical Body Diode Transfer Characteristics

Figure 5. Normalized  $R_{DS(on)}$  vs. TemperatureFigure 6. Normalized  $BV_{DSS}$  vs. Temperature

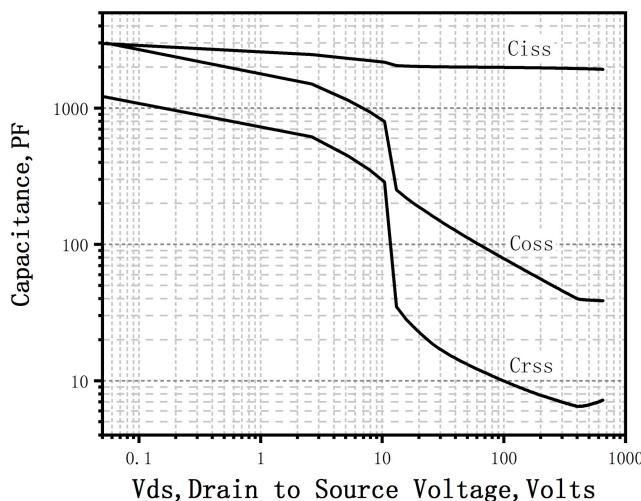


Figure 7. Capacitance Characteristics

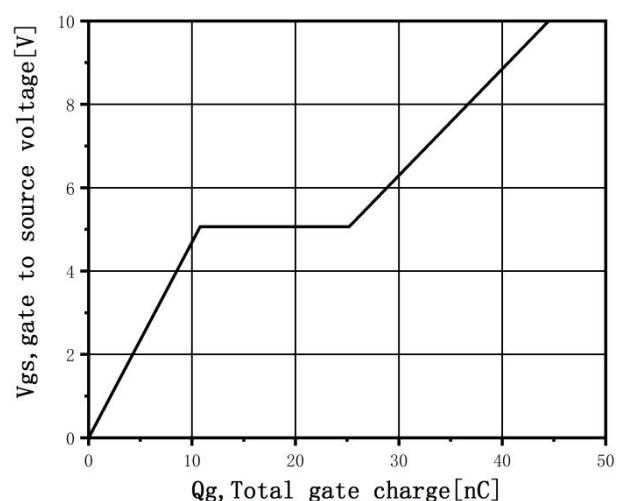
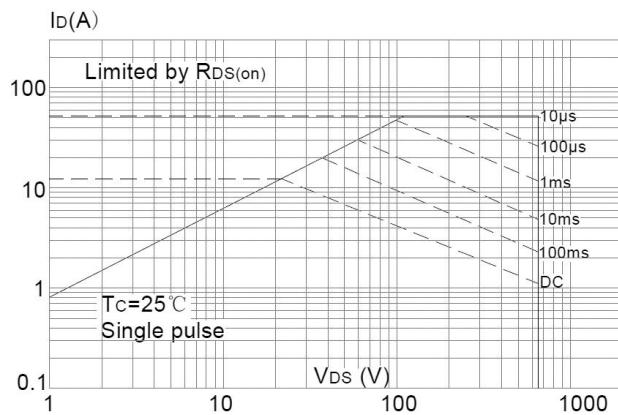
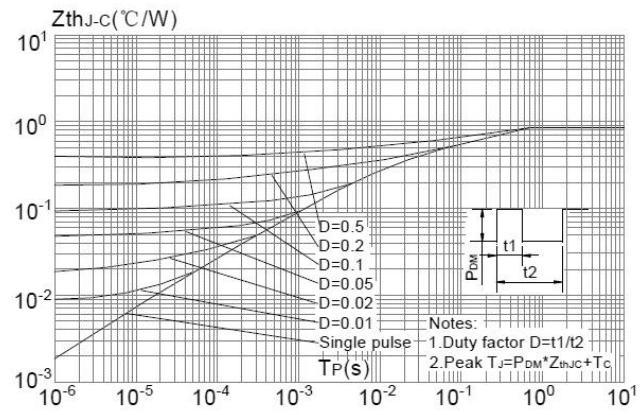
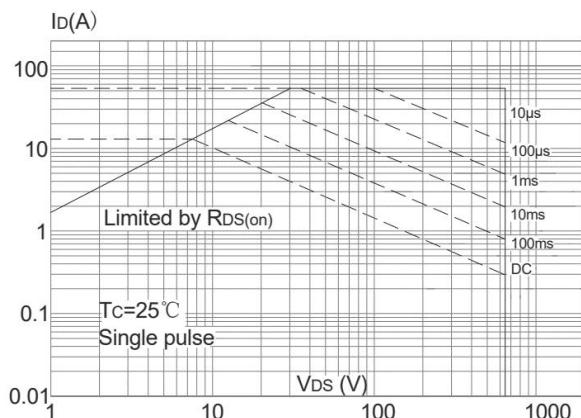
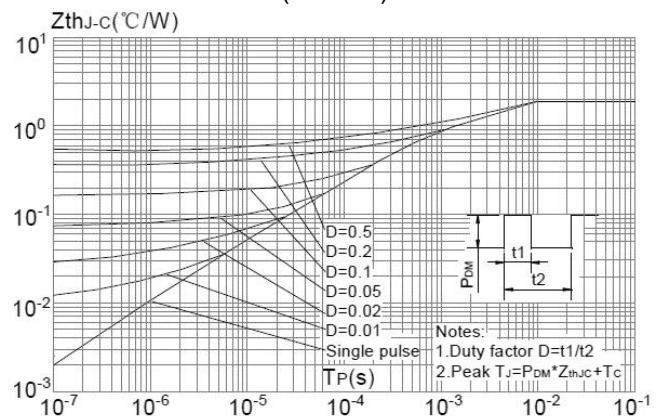
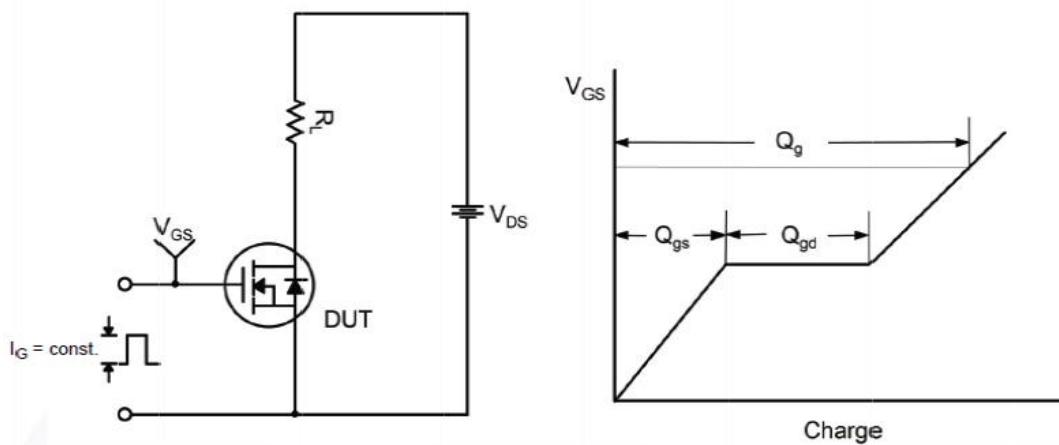


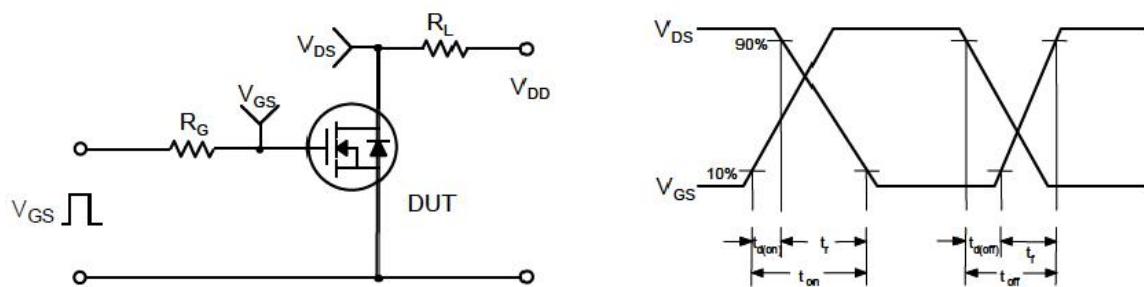
Figure 8. Gate Charge Characteristics

Figure 9. Maximum Safe Operating Area  
(TO-220)Figure 10. Transient Thermal Response Curve  
(TO-220)Figure 9. Maximum Safe Operating Area  
(TO-220F)Figure 12. Transient Thermal Response Curve  
(TO-220F)

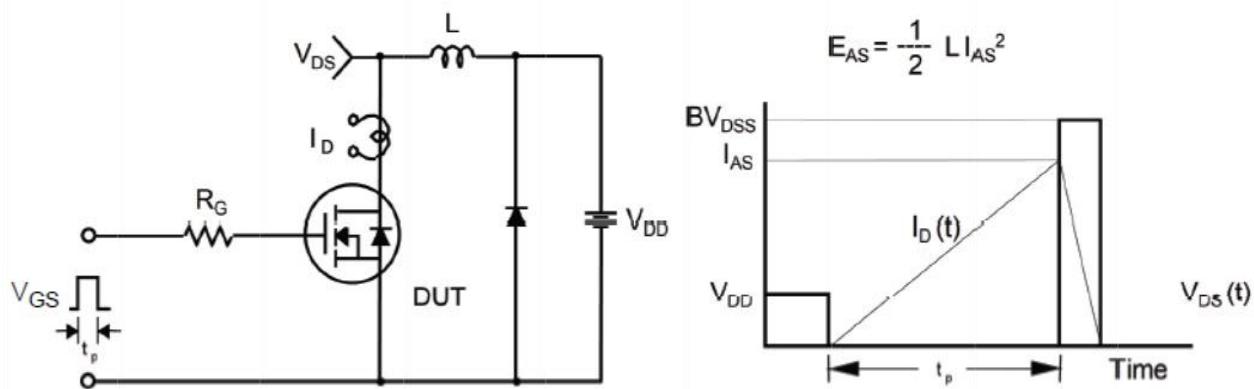
Gate Charge Test Circuit &amp;Waveform

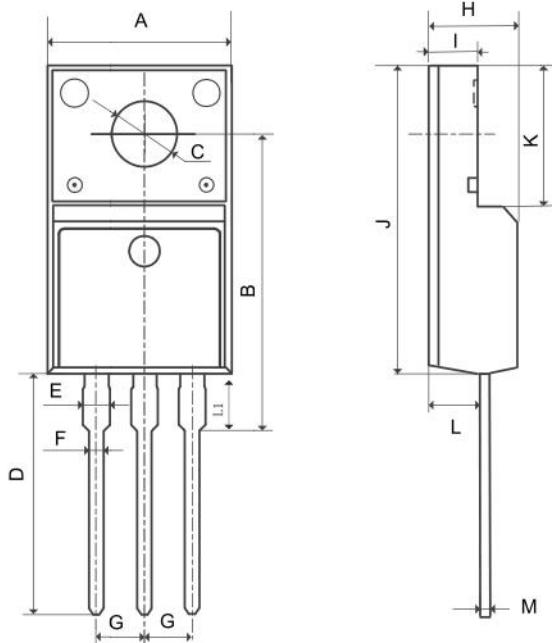


Switching Test Circuit &amp;Waveforms

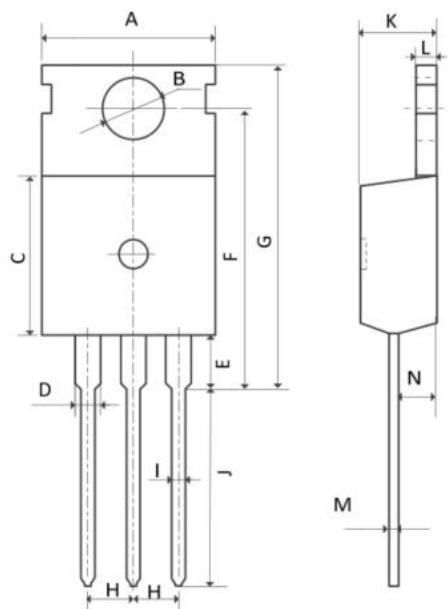


Unclamped Inductive Switching Test Circuit &amp;Waveforms



**Mechanical Dimensions for TO-220F****COMMON DIMENSIONS**

SYMBOL	MM	
	MIN	MAX
A	9.96	10.36
B	15.10	16.10
C	3.03	3.38
D	12.64	13.28
E	1.18	1.58
F	0.70	0.95
G	2.54REF	
H	4.50	4.90
I	2.34	2.74
J	15.57	16.17
K	6.70REF	
L	2.56	2.96
M	0.40	0.65
L1	2.85	3.45

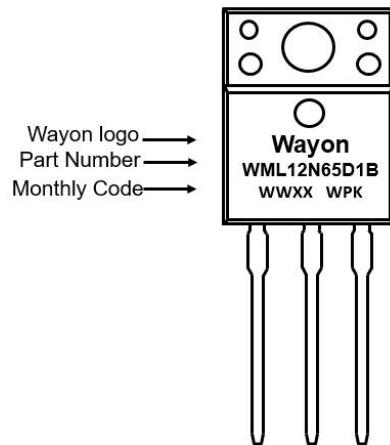
**Mechanical Dimensions for TO-220****COMMON DIMENSIONS**

SYMBOL	MM	
	MIN	MAX
A	9.70	10.20
B	3.40	3.80
C	8.90	9.40
D	1.17	1.47
E	2.60	3.40
F	15.10	16.70
G	19.55MAX	
H	2.54REF	
I	0.70	0.95
J	9.35	11.00
K	4.30	4.77
L	1.20	1.45
M	0.40	0.65
N	2.20	2.60

## Ordering Information

Part	Package	Marking	Packing method
WML12N65D1B	TO-220F	WML12N65D1B	Tube
WMK12N65D1B	TO-220	WMK12N65D1B	Tube

## Marking Information



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